

Alfred Binder

List of Publications by Year in descending order

Source: <https://exaly.com/author-pdf/10523989/publications.pdf>

Version: 2024-02-01

9
papers

78
citations

1937685

4
h-index

1720034

7
g-index

9
all docs

9
docs citations

9
times ranked

77
citing authors

#	ARTICLE	IF	CITATIONS
1	Die-Level Thinning for Flip-Chip Integration on Flexible Substrates. Electronics (Switzerland), 2022, 11, 849.	3.1	8
2	Evaluating Cu Printed Interconnects "Sinterconnects" versus Wire Bonds for Switching Converters. Electronics (Switzerland), 2022, 11, 1373.	3.1	1
3	Ultra-Thin Chips (UTC) Integration on Inkjet-Printed Papers. , 2022, , .		3
4	Sinterconnects: All-Copper Top-Side Interconnects Based on Copper Sinter Paste for Power Module Packaging. Energies, 2021, 14, 2176.	3.1	4
5	Flip Chip integration of ultra-thinned dies in low-cost flexible printed electronics; the effects of die thickness, encapsulation and conductive adhesives. Microelectronics Reliability, 2021, 123, 114204.	1.7	22
6	Exploiting the combination of 3D polymer printing and inkjet Ag-nanoparticle printing for advanced packaging. Microelectronic Engineering, 2017, 176, 1-5.	2.4	28
7	Digital micro-dispension of non-conductive adhesives (NCA) by inkjet printer. , 2017, , .		4
8	Fast Phase Analysis of SAW Delay Lines. Lecture Notes of the Institute for Computer Sciences, Social-Informatics and Telecommunications Engineering, 2016, , 373-382.	0.3	1
9	Phase stability comparison of SAW sensor evaluation with various CW type radars. Procedia Engineering, 2010, 5, 661-664.	1.2	7